1 Package summary

<table>
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<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
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<td>package length</td>
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<td>6.2</td>
<td>6.3</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
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<td>6.2</td>
<td>6.3</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
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<td>1.148</td>
<td>1.218</td>
<td>mm</td>
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<tr>
<td>nominal pitch</td>
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<td>0.9</td>
<td>-</td>
<td>mm</td>
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<tr>
<td>actual quantity of termination</td>
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<td>21</td>
<td>-</td>
<td></td>
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</table>
2 Package outline

Figure 1. Package outline HLLGA21R (SOT1996-1)
Figure 2. Package outline detail HLLGA21R (SOT1996-1)
3 Soldering

Figure 3. Reflow soldering footprint part1 for HLLGA21R (SOT1996-1)
Figure 4. Reflow soldering footprint part 2 for HLLGA21R (SOT1996-1)
Figure 5. Reflow soldering footprint part3 for HLLGA21R (SOT1996-1)
PLGA—21 I/O
6.2 x 6.2 x 1.148 PKG, 0.9 PITCH

NOTES:
1. ALL DIMENSIONS IN MILLIMETERS.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.

Figure 6. Package outline note HLLGA21R (SOT1996-1)
4 Legal information

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HLLGA21R, thermal enhanced low profile land grid array package, 21 terminals, 0.9 mm pitch, 6.2 mm x 6.2 mm x 1.148 mm body

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